

FSP-501

- FSP 501是Micro Thin底層樹脂塗層的SAP材料。
FSP501 is SAP(Semi Additive Process) material which is coated primer resin on Micro Thin.
- 適用於線寬/線距(L/ S) =20/20或以下之應用。
Usable for fine pitch pattern L/S=20/20 or less formation.

用途/Application

- IC封裝載板
/Semiconductor Package

構成/Composition



生產地點/Production Site

- 日本 / Japan

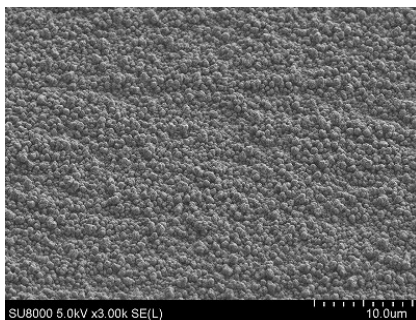
代表性特性數據/Representative

	μm	Area weight (w/o Primer) (g/m ²)	Laminate side Rz(μm)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm)@FR-4
FSP501	1.5	18	1.4	-	-	-
	2	21	1.4	-	-	-
	3	30	1.4	-	-	-

※上述表列為代表性數據非保證值
This is representative data, not guaranteed.

※Peel Strength為增鍍到35 μm 厚度之後的測試值
Evaluated after plated up to 35 μm .

底層樹脂塗層塗工前處理面/
Laminate side before Primer coat



阻劑面/ resist side

